APPLICATION FORM – Hong Kong Pavilion @ electronica 2018
electronica 2018 香港館展團申請表格

CONFIDENTIAL
密件

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Hong Kong Pavilion
Munich, Germany
November 13 - 16, 2018

Co-organisers:

HKTDC 香港貿發局

Messe München

HKTDC Contact: Ms. Karen Yau
Tel: +852 2584 4051
Fax: +852 2169 9491
Email: karen.yau@hktdc.org

MMIHK Contact: Ms. Garman Chan
Tel: +852 2511 5199
Fax: +852 2511 5099
Email: mmi_hk@mmiasia.com.sg

Application Deadline: November 30, 2017 (Thursday) 截止日期：2017 年 11 月 30 日 (星期四)

Important

◆ All information must be provided in English unless otherwise stated 除註明外，所有資料必須以英文填寫

◆ The "Company Name in English" will appear on the fascia at your booth 公司英文名稱將用作攤位之公司招牌

◆ Please send the completed application form and Hong Kong Business Registration copy to: 請填妥表格及香港商業登記証副本發送至：

1) Hong Kong Trade Development Council 香港貿易發展局
Email 電郵：karen.yau@hktdc.org / Fax 傳真：+852 2169 9491

or 或

2) MMI Asia Pte Ltd 慕尼黑國際博覽亞洲有限公司
Email 電郵：mmi_hk@mmiasia.com.sg / Fax 傳真：+852 2511 5099

◆ Please send the cheque payment to: 請將支票寄往：

Ms. Karen Yau, Hong Kong Trade Development Council
38/F, Office Tower, Convention Plaza, 1 Harbour Road, Wanchai, Hong Kong
香港灣仔港灣道路 1 號會展廣場辦公大樓 38 樓 香港貿易發展局 丘麗珠小姐收

◆ For enquiries 查詢請電: 1. HKTDC: Ms. Karen Yau +852 2584 4051 2. MMIHK: Ms. Garman Chan +852 2511 5199

A. Company Information 公司資料

1a. Company Name in English ____________________

1b. 公司中文名稱 ____________________

2. Registered Office Address 公司登記地址 ____________________

Correspondence Address 通訊地址 ____________________
☐ Same as above 同上

3. Tel No. 電話 ____________________ 4. Fax No. 傳真 ____________________

5. Email 電子郵件 ____________________

6. Website 網址 ____________________

7. Business Registration Certificate No. 商業登記證號碼 ________–___–___–___–__

8. Name of Holding/Subsidiary Companies in Hong Kong / Outside Hong Kong 香港/境外 分公司名稱 ____________________

9. No. of Office Worker 職員數目： In Hong Kong 香港 __________ Outside Hong Kong 境外 __________

10. No. of Factory Worker 工人數目： In Hong Kong 香港 __________ Outside Hong Kong 境外 __________

B. Nature of Business 業務性質

1. ☐ Importer 入口商
2. ☐ Exporter 出口商
3. ☐ Re-Exporter 轉口商
4. ☐ Manufacturer 生產商
   - ☐ Factory in Hong Kong 生產設施設於香港
   - ☐ Factory outside Hong Kong 生產設施設於香港境外
   - (Please specify 請註明) ____________________
5. ☐ Others 其他 (Please specify 請註明) ____________________

C. Export Sales Figures for the Past Two Years 過去兩年出口額（approx. are acceptable 約數）

1. 2015 HK$ ____________________
2. 2016 HK$ ____________________

D. Information of Contact Person for this Exhibition 是次展覽之聯絡人資料

1. Name *Mr. / Ms. ____________________ (Last Name) (First Name)

中文姓名 *先生/小姐 ____________________ (姓) (名)

2. Position 職位 ____________________

3. Direct Tel No. 直線電話 ____________________

4. Email 電子郵件 ____________________

5. Direct Fax No. 直線傳真 ____________________

<IMPORTANT> Email is our primary mode of contact, please provide an email address that is regularly checked!

** Please circle the appropriate answer *請圈出適用者*

E. Objective(s) of Joining this Exhibition 參加是次展覽之主要目的

1. ☐ Increase of sales 增加銷售額
2. ☐ Gain market exposure 獲取市場經驗
3. ☐ Conduct market study 市場考察
4. ☐ Appointment of agent/distributor 委任代理商/分銷商
5. ☐ Establish new contacts 建立新的業務聯繫
6. ☐ Launch new products 推出新產品
7. ☐ Promote company image 推廣公司形象
8. ☐ Test market potential 測試產品的市場潛力
9. ☐ Others 其他 (Please specify 請註明) ____________________

F. Product Category 產品類別

1. ☐ Electronic design (ED / EDA) (A3)
2. ☐ Test and measurement (A3, B3)
3. ☐ Power supplies (A5, A6)
4. ☐ Displays (B4)
5. ☐ Semiconductors (A4, B4, B5, C3, C4, C5)
6. ☐ Wireless (C3)
7. ☐ Automotive (B4)
8. ☐ Embedded systems (B5)
9. ☐ Micro-and nanosystems (B3)
10. ☐ Servo-technology / Drive elements (B3)
11. ☐ Sensor technology (B3)
12. ☐ Electromechanics / System peripherals
    - Casing technology (A2)
13. ☐ Electromechanics / System peripherals
    - Interconnection components / systems (B2, C2)
14. ☐ PCBs and other circuit carriers (A1, B1)
15. ☐ EMS Electronic manufacturing services (A1, B1)
16. ☐ Electromechanics / System peripherals
    - Relays, switches and keyboards (A2)
17. ☐ Passive components (A6, B6)
18. ☐ Services, assemblies & subsystems (all halls)

Brandname(s) 品牌名稱 ____________________

Details of Exhibits 展品詳情 ____________________

G. Existing Markets of the Products to be Promoted 有關產品的現有市場及比重

Country / Region 國家 / 地區 — **% of Total Sales** 佔總銷售額百分率

Asia 亞洲

1. ☐ Chinese mainland 中國內地 ____________
2. ☐ Hong Kong 香港 ____________
3. ☐ Japan 日本 ____________
4. ☐ Korea 韓國 ____________
5. ☐ Middle East 中東 ____________
6. ☐ South East Asia 東南亞 ____________
7. ☐ Taiwan 台灣 ____________
8. ☐ Others 其他亞洲國家 ____________

Americas 美洲

9. ☐ U.S.A. 美國 ____________
10. ☐ Mexico 墨西哥 ____________
11. ☐ Brazil 巴西 ____________
12. ☐ Others 其他美洲國家 ____________

Country / Region 國家 / 地區 — **% of Total Sales** 佔總銷售額百分率

Europe 歐洲

13. ☐ Germany 德國 ____________
14. ☐ U.K. 英國 ____________
15. ☐ The Netherlands 荷蘭 ____________
16. ☐ France 法國 ____________
17. ☐ Italy 意大利 ____________
18. ☐ Spain 西班牙 ____________
19. ☐ Others 其他歐洲國家 ____________

Others 其他

20. ☐ Africa 非洲 ____________
21. ☐ Australasia 大洋洲 ____________

H. Participation Fee & Deposits 參展費用及訂金/按金

		1st Payment 第一次付款	**2nd Payment** 第二次付款			
A	**B**	**C** = Bx50%	**D** = Bx50%	**E1**	**E2**	**D + E1 +E2**
Booth Size 攤位面積	**Participation Fee** 參展費	**Deposit** 訂金 **(50%)**	**Balance** 餘額 **(50%)**	**Misc Order Deposit** 雜項按金	**Corner Surcharge*** 轉角位付加費*	**Total 2nd Payment** 第二次付款合共
☐ 12 sqm (Standard Booth)	EUR 7,140.00	EUR 3,570.00	EUR 3,570.00	EUR 450.00	☐ 1-side n/a ☐ 2-sides EUR 714.00 ☐ 3-sides EUR 1,071.00	EUR 4,020.00 or EUR 4,734.00 or EUR 5,091.00
☐ ______ sqm (multiples of 3 sqm)	EUR ___________ (EUR 595 x ______ sqm)	EUR_______ (B x 50%)	EUR ________ (B x 50%)	EUR 450.00	☐ 1-side n/a ☐ 2-sides B x 10% ☐ 3-sides B x 15%	EUR ___________

Due Date 繳款日期：

C : **Deposit** — To be submitted with the application form

D + E : **Balance + Misc Deposit + Corner Surcharge** — Submitted with application in a post-dated cheque due on **June 1, 2018.**

*** Subject to availability at booth selection meeting** *視乎分配攤位情況而定

Important Notes

- The minimum stand-size booking for the Hong Kong Pavilion is 12 sqm. Normally, additional space available will be in the multiples of 3 sqm.
- Please send the completed application form and Hong Kong Business Registration copy to HKTDC or MMIHK on or before November 30, 2017. First payment (50% of participation fee) should be settled in full as with the submission of application to HKTDC.
- The co-organisers will at its discretion, allocate the stand to the exhibitors according to the size of the stand applied, sequence in which the application and payment are received and other prevailing factors and conditions.
- A post-dated cheque due on June 1, 2018 should be submitted together with application for settlement of second payment (50% of remaining participation fee + miscellaneous order deposit + corner surcharge, if applicable).
- Miscellaneous order deposit will be used to offset any other additional incidental expenses incurred by the exhibitor (for example, additional catalogue entry, additional stand facilities, etc). The co-organisers may at any time request an additional amount to be paid by the participant if the deposit is insufficient to settle the anticipated expenses. The participant is liable for the balance due to the co-organisers where the actual cost exceeds the deposit. In the event of surplus, the amount will be refunded accordingly. Such settlement will usually take two to six months after the exhibition.
- Exhibitor with payment not settled within the stated period will automatically be considered as having withdrawn.

Please send the application form and Hong Kong Business Registration copy to:

1) Hong Kong Trade Development Council

Email: karen.yau@hktdc.org / Fax: +852 2169 9491

or 2) MMI Asia Pte Ltd
Email: mmi_hk@mmiasia.com.sg / Fax: +852 2511 5099

And cheque payments to:

Hong Kong Trade Development Council (Attn: Ms. Karen Yau for electronica 2018)

38/F, Office Tower, Convention Plaza, 1 Harbour Road, Wanchai, Hong Kong

I. Bank Account Information 銀行戶口資料

Please indicate below details of the Hong Kong Dollar bank account to which any ***refund of excess deposits*** should be credited. 請填妥下列銀行戶口資料，作*日後退回剩餘的按金*之用

Name of Bank 銀行名稱 ____________________ Branch Name 分行名稱 ____________________

Account Name 戶口名稱 ____

Account Number 戶口號碼 □□□ — □□□ — □□□□□□□□□

Bank Code 銀行編號 Branch Code 分行編號 Account Code 戶口號碼

※ Please consult your bank if you are not sure of your bank and branch numbers 請向銀行查詢有關銀行及分行編號

We (Name of Company) ____

hereby apply to participate in the exhibition. We understand that the participation fee is non-refundable and agree to be bound by the provisions of all documents forming part of the application form, including but not limited to, the attached Participation Terms & Conditions.

We hereby declare that the information given in the application form is true and correct to the best of our knowledge. We understand that any false or misleading information given by us to you will lead to the rejection of our right to participate in the exhibition.

We understand that above information will be included into the co-organisers' databank and the co-organisers can make use of our information for trade promotion purposes.

Company Stamp & Authorized Signature
公司印章及負責人簽署 ____________________ Date 日期 ____________________

Full Name of Authorized Signer
負責人姓名 ____________________ Position Held
職位 ____________________

Participation Terms & Conditions

Application

1. Exhibitors wishing to take part in the exhibition must fully complete, sign and stamp the application form and send it to HKTDC or MMIHK on or before November 30, 2017.

Payment

1. First payment (50% of participation fee) should be settled in full as with the submission of application to HKTDC or MMIHK.

2. A post-dated cheque due on June 1, 2018 should be submitted together with application for settlement of second payment (50% of remaining participation fee + miscellaneous order deposit + corner surcharge, if applicable).

3. Miscellaneous order deposit will be used to offset any other additional incidental expenses incurred by the exhibitor (for example, additional catalogue entry, additional stand facilities, etc). The co-organisers may at any time request an additional amount to be paid by the participant if the deposit is insufficient to settle the anticipated expenses. The participant is liable for the balance due to the co-organisers where the actual cost exceeds the deposit. In the event of surplus, the amount will be refunded accordingly. Such settlement will usually take two to six months after the exhibition.

4. All payments should be made by crossed cheques payable to "Hong Kong Trade Development Council" and sent to:

   For Hong Kong Exhibitors
   Hong Kong Trade Development Council
   38/F, Office Tower, Convention Plaza,
   1 Harbour Road, Wanchai, Hong Kong
   Attn: Ms. Karen Yau

   or to "MMI Asia Pte Ltd" and sent to:

   For MMI's trade partner Exhibitors
   MMI Asia Pte Ltd
   Room 2811, Shui On Centre
   6-8 Harbour Road, Wanchai, Hong Kong
   Attn: Ms. Natalie Chan

Withdrawal

1. Exhibitors may withdraw from the exhibition by informing the co-organisers in writing. The withdrawal will take effect the day the letter arrives the co-organisers with the following conditions that:

   - The stand allocated to the exhibitor will be cancelled immediately. .
   - HKD 500 administrative fee together with other costs already incurred such as the official catalogue entry fee will be deducted from the miscellaneous order charge.
   - 50% of the stand charge already settled will be forfeited.
   - After the stand has been allocated to the exhibitor, the total stand charge including corner surcharge already settled be forfeited. However, if the co-organisers can find a new exhibitor for the replacement, 50% of the stand charge including corner surcharge already settled will be refunded to the exhibitor who withdraws from the exhibition.
   - All stand charge including corner surcharge will be forfeited for withdrawal within 3 months before the first day of the exhibition.

2. Exhibitors with payment not settled within the stated period will automatically be taken as withdrawn.

Exhibition Rule & Regulations

1. The co-organisers will at its discretion, allocate the stand to the exhibitors according to the size of the stand applied, sequence in which the application and payment are received and other prevailing factors and conditions. No requests of stand selection will be entertained. The co-organisers will try its best to serve the needs of the exhibitors in terms of their exhibition, freight forwarding, stand construction and traveling needs. However, the co-organisers will not be held accountable and liable for anything that is beyond control.

2. Exhibitors are not allowed to resell or sublet the allocated stands to another party.

3. Exhibitors are not allowed to distribute any non-Hong Kong Pavilion promotional materials within the pavilion area.

4. Exhibitors are not allowed to alter the basic stand design and construction of the Hong Kong Pavilion. Exhibitors are not allowed to stick any posters directly to the stand wall. All posters should be framed before being hung up. Any damage to these basic stand facilities will be claimed against the exhibitors.

5. Exhibitors are not allowed to leave any materials on top of the ceiling rails. In the event of an electricity failure, please inform the co-organisers immediately; do not attempt to reach the ceiling rails to fix it.

6. Exhibitors must exhibit throughout the entire exhibition period. Exhibitors who clear their stands before the end of the exhibition will be fined EUR 500 with their records marked.

7. Except for the stand construction materials, exhibitors must clear and dispose of all waste before leaving the exhibition hall. Any other waste materials left behind will be cleared by the official stand cleaning company with the bills sent to the exhibitors accordingly.

8. The co-organisers will not be held accountable for any printing errors in the official catalogue or pavilion mission catalogue.

9. Any other additional incidental costs incurred by the exhibitors including bank charges or currency conversion difference will be deducted from the miscellaneous order deposit.

10. The co-organisers is under no circumstances liable for damage to or loss of goods/exhibits brought to the trade fair by the exhibitor or the appointed forwarder. Exhibitors are advised to insure their own exhibits and to keep the exhibits in lockable cabinets or bring along them with themselves.

11. The co-organisers expects exhibitors to respect the industrial property rights of other exhibitors. Exhibitors will have to bare all legal responsibilities in cases of infringements.

12. Exhibitors must abide by the Hong Kong Pavilion participation terms and conditions. In case of any disputes, the event organiser, Messe München GmbH's participation terms and conditions, will be referred to.

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World's Leading Trade Fair for Electronic Components, Systems and Applications
November 13–16, 2018
Messe München
www.electronica.de

Messe München

Index of products and services Joint Pavilion Exhibitor

Organizer

Company
Hall / booth no.

Joint Pavilion Exhibitor

Company

Please check in which main product category you would like to be located (multiple responses possible).
Data for catalog listing will be requested separately.

If multiple categories, please indicate main category/focal area: **cat. no**

1 Semiconductors
- ☐ 1.1 Diodes (including diode networks)
- ☐ 1.2 Transistors
- ☐ 1.3 Power semiconductor components
- ☐ 1.4 Opto semiconductor components
- ☐ 1.5 Accessories for discrete semiconductors
- ☐ 1.6 Logic circuits
- ☐ 1.7 Microprocessors (see Embedded systems)
- ☐ 1.8 Memory (see Embedded systems)
- ☐ 1.9 Application-specific ICs (ASSP)
- ☐ 1.10 Data / signal transformer ICs
- ☐ 1.11 ICs, special designs (including ASICs / CSICs)

2 Embedded systems
- ☐ 2.1 Development tools, software
- ☐ 2.2 Development tools, hardware
- ☐ 2.3 Hardware
- ☐ 2.4 Peripheral systems
- ☐ 2.5 DDI and other network-technology components
- ☐ 2.6 Memories and memory peripherals
- ☐ 2.7 System solutions

3 Displays
- ☐ 3.1 Liquid Crystal Display (LCD)
- ☐ 3.2 Plasma Display Panel (PDP)
- ☐ 3.3 Cathode Ray Tube (CRT)
- ☐ 3.4 Vacuum Fluorescent Display (VFD)
- ☐ 3.5 Organic Light-Emitting Diode (OLED)
- ☐ 3.6 EL Display
- ☐ 3.7 Field Emission Display (FED)
- ☐ 3.8 Light Emitting Diode (LED)
- ☐ 3.9 E-Paper
- ☐ 3.10 Peripheral equipment for displays

4 Micro- and nanosystems
- ☐ 4.1 Microsystems
- ☐ 4.2 MEMS
- ☐ 4.3 Nanotechnology

5 Sensor technology
- ☐ 5.1 Sensors for geometrical parameters
- ☐ 5.2 Sensors for mechanical parameters
- ☐ 5.3 Sensors for time and time-based parameters
- ☐ 5.4 Sensors for temperature and caloric parameters
- ☐ 5.5 Sensors for climatic parameters
- ☐ 5.6 Sensors for optical and acoustic parameters
- ☐ 5.7 Sensors for electrical and magnetical parameters
- ☐ 5.8 Sensors for chemical parameters
- ☐ 5.9 Sensors for biological parameters
- ☐ 5.10 Sensor elements by technology

6 Test and measurement
- ☐ 6.1 Measuring / testing of geometric parameters
- ☐ 6.2 Mechanical parameters
- ☐ 6.3 Time and time-based parameters
- ☐ 6.4 Thermal units
- ☐ 6.5 Environmental parameters
- ☐ 6.6 Chemical and biological parameters
- ☐ 6.7 Optical and acoustical parameters
- ☐ 6.8 Image / pattern recognition and processing
- ☐ 6.9 Electrical parameters
- ☐ 6.10 Specialized laboratory / test equipment

7 Electronic Design (ED / EDA)
- ☐ 7.1 CAD / CAE tools
- ☐ 7.2 Generation software
- ☐ 7.3 Test software
- ☐ 7.4 Software for special applications
- ☐ 7.5 Peripheral equipment for ED / EDA environments
- ☐ 7.6 ED / EDA services
- ☐ 7.7 Design and development systems

8 Passive components
- ☐ 8.1 Inductors and accessories
- ☐ 8.2 Capacitors
- ☐ 8.3 Resistors (including R networks)
- ☐ 8.4 Radiofrequency and microwave components
- ☐ 8.5 Polymer components
- ☐ 8.6 Nonlinear high-voltage components
- ☐ 8.7 Passive components, miscellaneous
- ☐ 8.8 Piezoelectric components
- ☐ 8.9 Magnetic and electro ceramic products

9 Electromechanics / System peripherals
9.1 Relays, Switches and keyboards
- ☐ 9.1.1 Switches for continuous connection
- ☐ 9.1.2 Switches with additional functions
- ☐ 9.1.3 Electrical keys
- ☐ 9.1.4 Detector components
- ☐ 9.1.5 Detector and signaling devices
- ☐ 9.1.6 Keyboards
- ☐ 9.1.7 Components and accessories for keyboards
- ☐ 9.1.8 Initiation devices, manually activated
- ☐ 9.1.9 Relays

Your application cannot be processed without completed index of products and services.

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Index of products and services Joint Pavilion Exhibitor

Organizer

Company ______ Hall / booth no. ______

Joint Pavilion Exhibitor

Company ______

Please check in which main product category you would like to be located (multiple responses possible).
Data for catalog listing will be requested separately.

If multiple categories, please indicate main category/focal area: **cat. no** ______

9.2 Interconnection components / systems
☐ 9.2.1 Standardized connectors
☐ 9.2.2 Connectors for specific handling
☐ 9.2.3 Connectors, PCB-mountable
☐ 9.2.4 Sockets
☐ 9.2.5 Connectors, application-oriented
☐ 9.2.6 Connectors for telecommunications
☐ 9.2.7 Cables with connectors
☐ 9.2.8 Connectors with additional functions
☐ 9.2.9 Connectors, specific forms
☐ 9.2.10 Miscellaneous connectors
☐ 9.2.11 Accessories for connectors
9.3 Interconnection components, specialized
☐ 9.3.1 Terminals
☐ 9.3.2 Connection elements, miscellaneous
☐ 9.3.3 Accessories
☐ 9.3.4 Cables
9.4 Casing technology
☐ 9.4.1 System racks
☐ 9.4.2 Build-in and desktop housings
☐ 9.4.3 Small-scale housings
☐ 9.4.4 Special housings
☐ 9.4.5 Accessories for housings
☐ 9.4.6 Thermal management
☐ 9.4.7 Electronic protection devices (EMI / ESD)

10 Power supplies
☐ 10.1 Transformers
☐ 10.2 Coilware for specific applications
☐ 10.3 Accessories for coilware
☐ 10.4 Power supplies, DC output
☐ 10.5 Power supplies, AC output
☐ 10.6 Frequency converters
☐ 10.7 UPS systems
☐ 10.8 Special power supplies
☐ 10.9 Batteries
☐ 10.10 Static current supplies, miscellaneous
☐ 10.11 Power management systems
☐ 10.12 Accessories

11 PCBs and other circuit carriers
☐ 11.1 Non-PTH single- and double-sided PCBs
☐ 11.2 Double-sided PCBs, PTH
☐ 11.3 Multilayer PCBs (ML)
☐ 11.4 Special PCBs
☐ 11.5 Injection molded circuits, MID / 3D-MID
☐ 11.6 Ceramic PCBs
☐ 11.7 PCBs for backplanes / bus systems
☐ 11.8 Accessories for PCBs

12 EMS Electronic manufacturing services
☐ 12.1 EMS (component / chip carrier manufacturing)
☐ 12.2 EMS (component construction and equipment manufacturing)
☐ 12.3 Product development
☐ 12.4 Intermediate / semifinished goods, materials
☐ 12.5 Hybrid components / assemblies
☐ 12.6 Prototyping

13 Assemblies and subsystems
☐ 13.1 Assemblies for control applications
☐ 13.2 Printer assemblies
☐ 13.3 Assemblies, miscellaneous
☐ 13.4 Hybrid modules (including multi-chip modules)
☐ 13.5 Servo-technology / Drive elements

14 Automotive
☐ 14.1 Drive (engine and gears)
☐ 14.2 Chassis / Steering
☐ 14.3 Brake
☐ 14.4 Interior / Comfort
☐ 14.5 Body / Safety
☐ 14.6 Active safety
☐ 14.7 Electrical on-board power supply
☐ 14.8 Construction and test

15 Wireless
☐ 15.1 Cellular systems
☐ 15.2 Non-cellular systems
☐ 15.3 Wireless applications
☐ 15.4 Business partners

16 Services
☐ 16.1 Information
☐ 16.2 Institutions / Organizations
☐ 16.3 Business concepts / Business development
☐ 16.4 Electronics development / approval / testing / certification
☐ 16.5 Services

Your application cannot be processed without completed index of products and services.

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